Special Issue

Emerging Packaging and Interconnection Technology

Message from the Guest Editors

As the integrated circuit industry becomes increasingly oriented by the "More than Moore" wave, electronic packaging is under the spotlight more than ever. This particular industrial sector is developing a fusion with cutting-edge micro/nano-scale science and engineering, with a significant impact on modern manufacturing. This Special Issue aims to provide a forum for the researchers and engineers of microelectronics packaging to share their latest ideas and discoveries, with an emphasis on advanced science and technology at the micro/nano-scale, a major topic covered by the journal *Micromachines*. In this Special Issue, original research articles and reviews are welcome. Research areas may include (but are not limited to) the following: design and implementation of new packaging architecture, advanced chip-to-substrate interconnection, high-density and low-temperature interconnection, micro/nano-structures for surface and interface engineering in packaging, new materials and processes of advanced packaging, modeling and simulation, heterogeneous integration, MEMS packaging and integration, packaging reliability, and manufacturing tooling.

Guest Editors

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You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

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